EPOXY TECHNOLOGY

DATA SHEET

EPO-TEK 360ST

Thixotropic Epoxy Adhesive

Rev. II
9/99

TYPICAL PROPERTIES

(To be used as a guideline only)

NUMBER OF COMPONENTS	Two
MIXING RATIO	PARTS BY WEIGHT
Part "A"	100
Part "B"	10
CURE SCHEDULE (minimum bond line temperature - use one of the following)	
150°C	5 minutes
120°C	10 minutes
100°C	30 minutes
PHYSICAL PROPERTIES	
Color	Amber
Consistency	slightly thixotropic paste
Viscosity @ 100 rpm/23°C	1,400 - 3,700 cPs
Specific Gravity	
Part "A"	1.11
Part "B"	1.02
Glass Transition Temp. (Tg) cured @ 150°C/1 hour	> 80°C
Lap Shear Strength (Al to Al)	2,500 psi
Tensile Strength	10,000 psi
Percent Elongation	4.2
Flexural Strength	18,000 psi
Heat Deflection Temp.	150°C
Water Absorption 24 hr. / 25°C	0.005%
2 hr. / 100°C	0.1%
ELECTRICAL PROPERTIES	
Volume Resistivity	3.88 x 10^{14} ohm-cm
Dielectric Strength	450 V/mil
Dielectric Constant (1 MHz)	3.7
Power Factor (1 MHz)	0.003
Loss Factor (1 MHz)	0.009
POT LIFE	3-4 hours

SHELF LIFE
One year when stored at room temperature.

DO NOT REFRIGERATE

EPO-TEK 360ST is a two component, slightly thixotropic epoxy with limited flow characteristics. The 100% solids epoxy system is designed for use in production applications where a long pot life, a short cure cycle and good handling properties are highly desirable. A unique feature of EPO-TEK 360ST is the dark red color that appears on curing. Cure by color instead of time. This color changing characteristic can be very desirable as a quality control tool in production applications.

EPO-TEK 360ST is a very reactive system only when heat is applied. It is therefore recommended to be used primarily in thin and thick film applications — adhesives, sealants, coatings, inks and in laminating. It can also be used as a binder for many different types of metallic and oxide pigments.

EPO-TEK 360ST can be applied by brush, spatula, screen printing and letter press techniques as 100% solids — no solvents or thinners are used. It can be used in the 400°F range.

EPO-TEK 360ST has good adhesion to many different types of substrates including metals, ceramics, glass and most plastics. It is highly recommended for bonding *NOMEX to NOMEX and NOMEX to copper and aluminum.

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Änderungen vorbehalten / Stand : 29.07.2004

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